

Evaluation of a hemispherical-shaped array sensor for photoacoustic tomography

光超音波トモグラフィ用半球型アレイセンサの評価

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1. Introduction

In order to obtain a three-dimensional image (3D) with high resolution by photoacoustic tomography, an ultrasonic sensor has three technical problems that we should get over as follows;

(1) To fabricate a hemispherical-shaped array sensor for detecting signals propagating in various directions from various shaped absorbers such as blood vessels,

(2) To arrange piezoelectric transducers as many as possible within a hemispherical shape for obtaining a 3D image with high resolution,

(3) To realize a broadband sensor to be able to receive wide ultrasonic waves from low frequency to high frequency, because of ultrasonic frequency changes according to size of observation object.

And so, ImPACT has conducted image quantitative evaluation by the hemispherical-shaped array sensor they developed using the piezoelectric element.

Besides, as part of the outgoing inspection, they evaluated the performance of 1024ch at variance with the echo from the metal ball using the focusing probe of non-destructive inspection.

2. Development of hemispherical-shaped array sensor

Conventional piezoelectric transducers in a product made of ceramics with piezoelectrical effect are hard and it was difficult to mold them as a spherical shape. We developed a new fabrication technology that combines the mold method with the flexible sheet of piezoelectric transducers¹⁾, such as **Fig. 1** and realized a hemispherical shape sensor that has 1024 channels within a hemispherical shape with a diameter of 110mm, such as **Fig. 2**. The flexible sheet was made of 1-3 composite transducer and its center frequency is 3.34MHz with 85% bandwidth, such as **Fig. 3**. The hemispherical-shaped array sensor was installed in a photoacoustic imaging system and realized 3D real-time imaging²⁾. The



Fig. 1 Flexible sheet of piezoelectric transducers

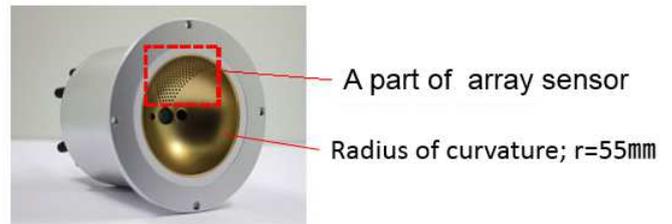


Fig.2 Hemispherical-shaped array sensor

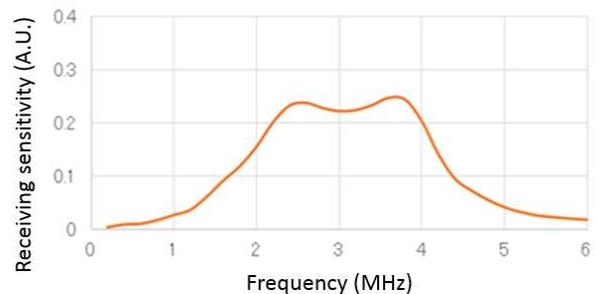


Fig.3 Frequency band of the composite transducer

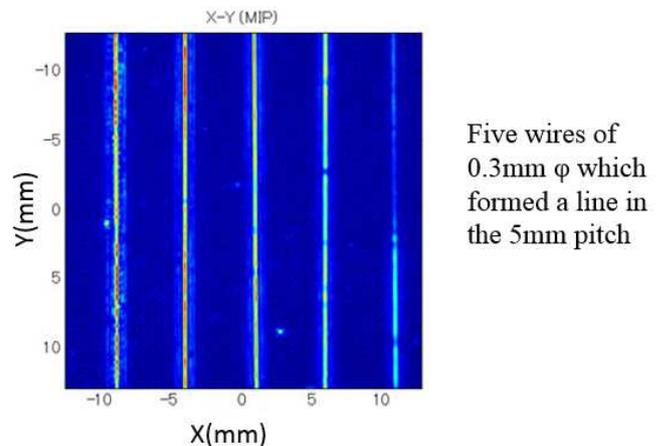


Fig.4 Image by photoacoustic imaging system

image is shown in Fig.4 the wire at $\phi 0.3$ can be confirmed.

3. Evaluation of hemispherical-shaped array sensor

This sensor is connected by 128ch in each group for a total of eight coaxial cables, and the connector is located on for each of them. You can assess 128ch in a second by getting the echo from the stainless ball at $\phi 10$, using the multiplexer, such as Fig.5. You should place the ball target in the focusing location in the same way of non-destructive inspection method using the focusing probe and, then you should adjust A-mode or the location shown in Fig. 7 by using the holder shown in Fig.6.

An example of measurement is shown in Fig.8. As the measurement result of 128ch, voltage peak of receiving for each of ch's echo was ; AVG=0.756(V), MAX=0.966(V), MIN=0.608(V), STDEV = 0.097V. The performance value at variance from the average value is the maximum of +2.1dB, the minimum of -1.3dB, STDEV 13%, and 1.05dB. it's typically accepted at less than 4 dB in an array probe's insepction, and so, It'll be accepted it because the maximum value at variance is 3.5dB.

And, this value is for the transmit-receive sensitivity but the performance value at variance for receiving is assumed at 1.8 dB and we realized that it's uniform in the value because the receive-only's evaluated for the photoacoustic technique.

4. Summary

We can create 1024ch's hemispherical-shaped array sensor by using flexible piezoelectric element and, realized 3D real-time imaging.

And, we also could confirm that echo valuation method allows us to conduct the outgoing inspection without any laser equipment.

Acknowledgment

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References

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2. Kenichi Nagae, "Technology development of Photoacoustic imaging system in CANON", Proc. of 2018 IEEE International Ultrasonics Symp. Oct.22-25,2018,Koube,Japan.(Invited)

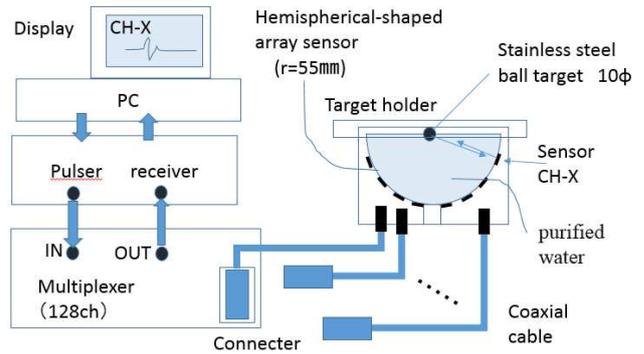


Fig.5 Block diagram of the evaluation equipment

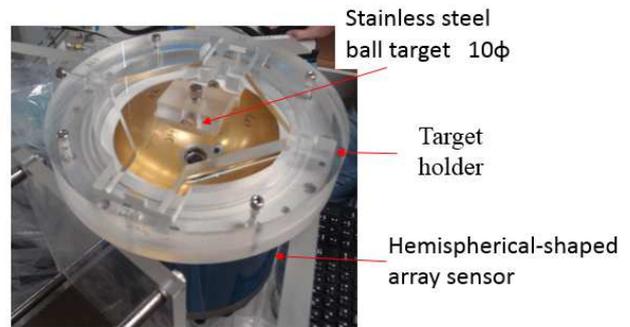


Fig.6 Set of the holder to hemispherical-shaped array sensor

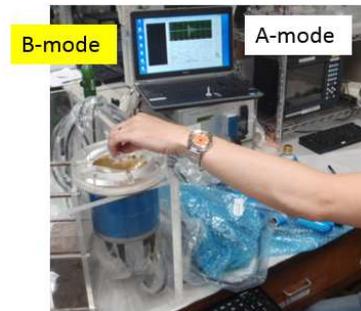


Fig.7 Central set of the ball target

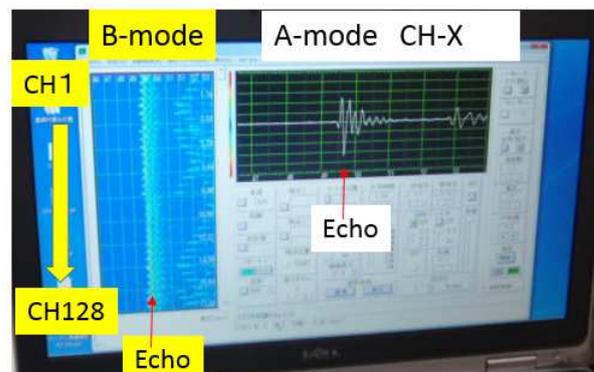


Fig.8 An example of the measurement screen